

IN THE CLAIMS:

Please amend the claims as indicated in the ensuing listing of the claims, which is intended to replace all prior claims listings.

1. (Previously presented) A semiconductor device component, comprising:
a substrate having a surface with contact pads exposed thereto; and
at least one stabilizer protruding from the surface and positioned between a periphery of the
surface and each contact pad exposed to the surface and including a plurality of at least
partially superimposed, contiguous, mutually adhered layers of the same type of dielectric
material.
2. (Previously presented) The semiconductor device component of claim 1, wherein
the at least one stabilizer protrudes from the surface a distance no more than a distance that at
least one conductive structure to be disposed in contact with at least one of the contact pads will
extend beyond the surface.
3. (Previously presented) The semiconductor device component of claim 2, wherein
the at least one stabilizer protrudes from the surface a distance that permits conductive structures
on the contact pads to contact conductors of another semiconductor device component upon
assembly of the substrate with the another semiconductor device component such that the surface
of the assembly faces a conductor-bearing surface of the another semiconductor device
component.
4. (Canceled)
5. (Previously presented) The semiconductor device component of claim 1, wherein
the at least one stabilizer comprises a photocurable material.
6. (Canceled)

7. (Previously presented) The semiconductor device component of claim 1, wherein the at least one stabilizer is positioned proximate a corner of the surface.

8. (Previously presented) The semiconductor device component of claim 1, wherein the at least one stabilizer has a cross-sectional shape of one of quadrilateral, round, oval, and triangular.

9. (Previously presented) The semiconductor device component of claim 1, wherein the at least one stabilizer is elongated in a direction parallel to the surface.

10. (Previously presented) The semiconductor device component of claim 1, further comprising protruding conductive structures in contact with selected ones of the contact pads.

11. (Previously presented) The semiconductor device component of claim 10, wherein the conductive structures comprise at least one of solder bumps, conductive columns, conductor-filled columns, and z-axis conductive adhesive.

12. (Previously presented) The semiconductor device component of claim 1, wherein the substrate comprises a semiconductor wafer with a plurality of dice thereon.

13. (Currently amended) A semiconductor device component, comprising:
a substrate having a surface with contact pads exposed thereto, the contact pads being configured to be connected with conductors on a surface of another semiconductor device component; and
at least one stabilizer protruding from the surface of the substrate and positioned between a periphery of the surface and the contact pads, the at least one stabilizer comprising a plurality of superimposed, contiguous, mutually adhered layers, each of which comprises the same type of dielectric material.

14. (Previously presented) The semiconductor device component of claim 13, wherein the at least one stabilizer protrudes from the surface of the substrate a distance no more than a distance that at least one conductive structure to be disposed in contact with at least one of the contact pads will extend beyond the surface.

15. (Previously presented) The semiconductor device component of claim 14, wherein the at least one stabilizer protrudes from the surface of the substrate a distance that permits conductive structures on the contact pads to contact the conductors of the another semiconductor device component.

16. (Previously presented) The semiconductor device component of claim 13, wherein the at least one stabilizer comprises a dielectric material.

17. (Previously presented) The semiconductor device component of claim 13, wherein the at least one stabilizer comprises a photocurable material.

18. (Previously presented) The semiconductor device component of claim 13, wherein the at least one stabilizer is positioned proximate a corner of the surface of the substrate.

19. (Previously presented) The semiconductor device component of claim 13, wherein the at least one stabilizer has a cross-sectional shape of one of quadrilateral, round, oval, and triangular.

20. (Previously presented) The semiconductor device component of claim 13, wherein the at least one stabilizer is elongated in a direction parallel to the surface.

21. (Previously presented) The semiconductor device component of claim 13, further comprising protruding conductive structures in contact with selected ones of the contact pads.

22. (Previously presented) The semiconductor device component of claim 21, wherein the conductive structures comprise at least one of solder bumps, conductive columns, conductor-filled columns, and z-axis conductive adhesive.

23. (Previously presented) The semiconductor device component of claim 13, wherein the substrate comprises a semiconductor wafer with a plurality of dice thereon.

24. (Previously presented) The semiconductor device component of claim 13, wherein the at least one stabilizer maintains a substantially uniform distance between the surface of the substrate and the surface of the another semiconductor device component.

25. (Currently amended) A semiconductor device component, comprising:
a substrate having a surface with contact pads exposed thereto, the contact pads being configured to be connected with conductors on a first surface of another semiconductor device component, each contact pad of the semiconductor device component being arranged substantially in-line with a plurality of other contact pads and positioned proximate to a center line of the substrate; and
at least one nonconductive stabilizer protruding from the surface of the substrate and positioned between a periphery of the surface and the contact pads, the at least one nonconductive stabilizer comprising ~~an elongate element which extends in a direction parallel to a surface of the substrate~~ a plurality of adjacent, mutually adhered regions comprising the same type of material.

26. (Previously presented) The semiconductor device component of claim 25, wherein the at least one stabilizer is configured so that voids do not occur in an insulative underfill material when the insulative underfill material is flowed into a space created when the substrate is connected with the another semiconductor device component.

27. (Previously presented) The semiconductor device component of claim 25, wherein the at least one stabilizer protrudes from the surface of the substrate a distance no more than a distance that at least one conductive structure to be disposed in contact with at least one of the contact pads will extend beyond the surface.

28. (Previously presented) The semiconductor device component of claim 27, wherein the at least one stabilizer protrudes from the surface a distance that permits conductive structures on the contact pads to contact the conductors of the another semiconductor device component.

29. (Previously presented) The semiconductor device component of claim 25, wherein the at least one stabilizer comprises a dielectric material.

30. (Previously presented) The semiconductor device component of claim 25, wherein the at least one stabilizer comprises a photocurable material.

31. (Currently amended) A semiconductor device component, comprising:
a substrate having a surface with contact pads exposed thereto, ~~the contact pads being arranged substantially in line with one another and positioned proximate to a center line of the substrate; and~~
at least one stabilizer protruding from the surface, ~~comprising an elongate structure which extends in a direction parallel to a plane of the surface, and being positioned between a periphery of the surface and all of the contact pads and including a plurality of adjacent, mutually adhered regions formed from the same material.~~

32. (Canceled)